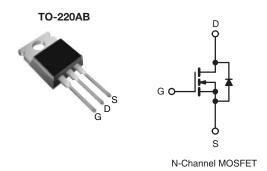
COMPLIANT

HALOGEN FREE



D Series Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	550				
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V 0.4				
Q _g max. (nC)	58				
Q _{gs} (nC)	8				
Q _{gd} (nC)	14				
Configuration	Single				



FEATURES

- Optimal Design
 - Low Area specific On-Resistance
 - Low Input Capacitance (Ciss)
 - Reduced Capacitive Switching Losses
 - High Body Diode Ruggedness
 - Avalanche Energy Rated (U_{IS})
- Optimal Efficiency and Operation
 - Low Cost
 - Simple Gate Drive Circuitry
 - Low Figure-Of-Merit (FOM): Ron x Qg
 - Fast Switching
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* Lead (Pb)-containing terminations are not RoHS-compliant. Exemptions may apply.

APPLICATIONS

- Consumer Electronics
 - Displays (LCD or Plasma TV
- Server and Telecom Power Supplies
 - SMPS
- Industrial
 - Welding, Induction Heating, Motor Drives
- Battery Chargers

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	SiHP14N50D-E3
Lead (Pb)-free and Halogen-free	SiHP14N50D-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	500		
Gate-Source Voltage			V _{GS}	± 30	V	
Gate-Source Voltage AC (f > 1 Hz)	30					
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	I _D	14	А	
	V _{GS} at 10 V	T _C = 100 °C		9		
Pulsed Drain Current ^a			I _{DM}	38		
Linear Derating Factor				1.6	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	56	mJ	
Maximum Power Dissipation			P_{D}	208	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	°C	
Drain-Source Voltage Slope T _J = 125 °C		dV/dt	24	V/ns		
Reverse Diode dV/dt ^d			0.4			
Soldering Recommendations (Peak Temperature) for 10 s				300°	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 2.3 mH, R_g = 25 Ω , I_{AS} = 7 Å.
- c. 1.6 mm from case.
- d. $I_{SD} \leq I_{D},$ starting T_{J} = 25 °C.



Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W		
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.6	C/VV		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				•	•		
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 250 μA		0.58	-	V/°C
Gate Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		-	5.0	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V		-	± 100	nA
7 0		V _{DS} =	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 400 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 7 A	-	0.320	0.40	Ω
Forward Transconductancea	9 _{fs}	V _{DS}	s = 50 V, I _D = 7 A	-	5.2	-	S
Dynamic		•				l	
Input Capacitance	C _{iss}		V _{GS} = 0 V,	-	1144	-	
Output Capacitance	C _{oss}	1	$V_{DS} = 100 \text{ V},$	-	100	-	
Reverse Transfer Capacitance	C _{rss}	1	f = 1 MHz	-	12	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{GS} = 0 V, V _{DS} = 0 V to 480 V		-	87	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	125	-	
Total Gate Charge	Qg			-	29	58	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 7 \text{ A}, V_{DS} = 400 \text{ V}$		8	-	nC
Gate-Drain Charge	Q _{gd}				14	-	
Turn-On Delay Time	t _{d(on)}			-	16	32	ns
Rise Time	t _r	V _{DD}	= 400 V, I _D = 7 A,	-	27	54	
Turn-Off Delay Time	$t_{d(off)}$		$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		29	58	115
Fall Time	t _f				26	52	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	1.7	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	14	
Pulsed Diode Forward Current	I _{SM}			-	-	56	- A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 7 A, V _{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C, } I_F = I_S = 7 \text{ A,}$ $dI/dt = 100 \text{ A/µs, } V_R = 20 \text{ V}$		-	319	-	ns
Reverse Recovery Charge	Q _{rr}			_	3.0	-	μC
Reverse Recovery Current	I _{RRM}			_	18	_	Α

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

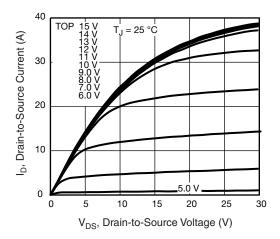


Fig. 1 - Typical Output Characteristics

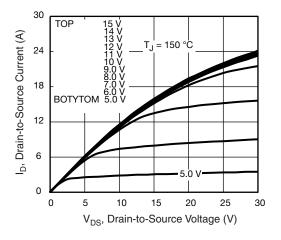


Fig. 2 - Typical Output Characteristics

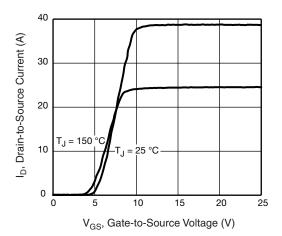


Fig. 3 - Typical Transfer Characteristics

S12-1229-Rev. A, 21-May-12

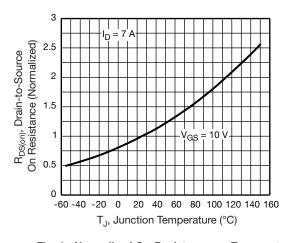


Fig. 4 - Normalized On-Resistance vs. Temperature

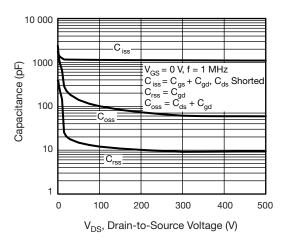


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

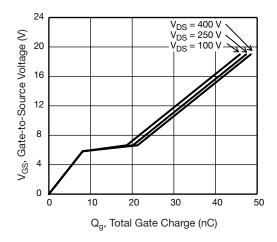


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



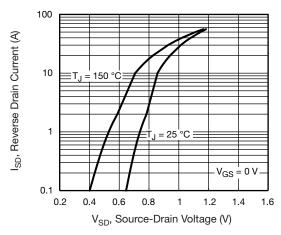


Fig. 7 - Typical Source-Drain Diode Forward Voltage

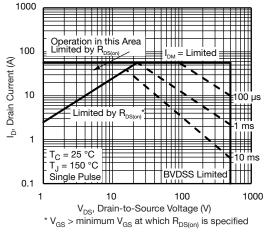


Fig. 8 - Maximum Safe Operating Area

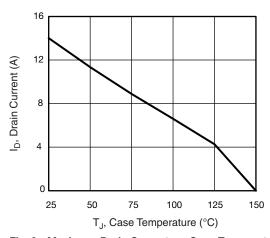


Fig. 9 - Maximum Drain Current vs. Case Temperature

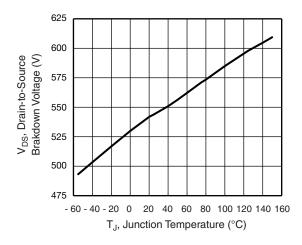


Fig. 10 - Temperature vs. Drain-to-Source Voltage

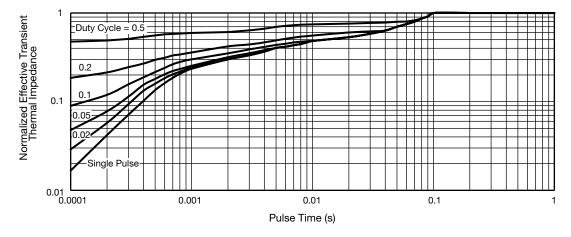


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



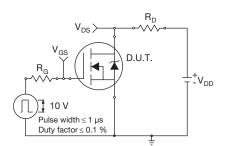


Fig. 12 - Switching Time Test Circuit

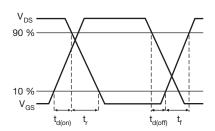


Fig. 13 - Switching Time Waveforms

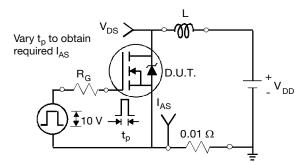


Fig. 14 - Unclamped Inductive Test Circuit

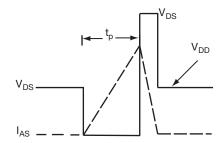


Fig. 15 - Unclamped Inductive Waveforms

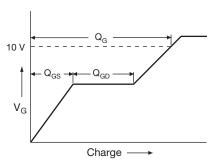


Fig. 16 - Basic Gate Charge Waveform

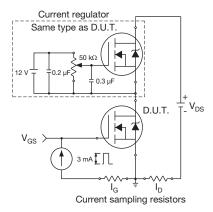
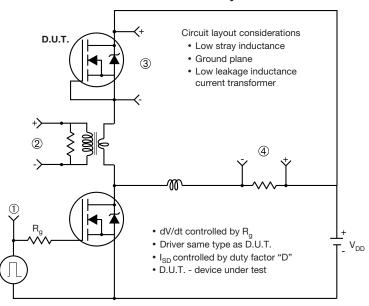


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



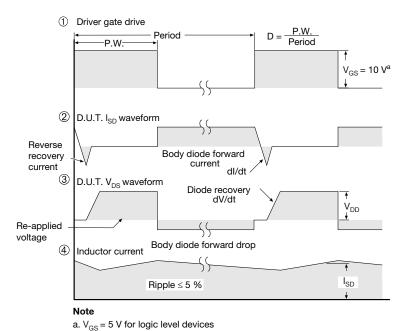


Fig. 18 - For N-Channel

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TO-220-1



DIM	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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